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APPLICATION NO.	FILI	NG DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/821,751	04	/08/2004	Jeremie James Dalton	101.114	1874	
75	90	06/15/2005		EXAMINER		
Thomas Swens			YEVSIKOV, VICTOR V			
1118 13th Stree Boulder, CO 8				ART UNIT PAPER NUMBER		
				2891		
				DATE MAILED: 06/15/2005	DATE MAILED: 06/15/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	
			an
Office Action Summany	10/821,751	DALTON ET AL.	Chira
Office Action Summary	Examiner	Art Unit	
	Victor V. Yevsikov	2891	
The MAILING DATE of this communication a Period for Reply	ppears on the cover sheet with the	correspondence addr	ess
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a relif NO period for reply is specified above, the maximum statutory perions are period to reply within the set or extended period for reply will, by state Any reply received by the Office later than three months after the main earned patent term adjustment. See 37 CFR 1.704(b).	I. 1.136(a). In no event, however, may a reply be eply within the statutory minimum of thirty (30) did will apply and will expire SIX (6) MONTHS froute, cause the application to become ABANDON	timely filed ays will be considered timely. m the mailing date of this comi IED (35 U.S.C. § 133).	nunica ti on.
Status			
1) Responsive to communication(s) filed on <u>08</u>	<u> April 2004</u> .		•
·	nis action is non-final.		
3) Since this application is in condition for allow	•		nerits is
closed in accordance with the practice under	Ex parte Quayle, 1935 C.D. 11,	453 O.G. 213.	
Disposition of Claims			
4) Claim(s) 1-41 is/are pending in the application	on.		
4a) Of the above claim(s) is/are withdr	rawn from consideration.		
5) Claim(s) is/are allowed.		•	
6) Claim(s) <u>1-4,6-18,20-22 and 31-41</u> is/are rej	ected.		
7) Claim(s) <u>5,19 and 23-30</u> is/are objected to.			
8) Claim(s) are subject to restriction and	or election requirement.		
Application Papers	•		
9) The specification is objected to by the Examir	ner.		
10)⊠ The drawing(s) filed on <u>08 April 2004</u> is/are:		by the Examiner.	
Applicant may not request that any objection to th	e drawing(s) be held in abeyance. S	ee 37 CFR 1.85(a).	
Replacement drawing sheet(s) including the corre		•	• •
11) The oath or declaration is objected to by the I	Examiner. Note the attached Office	e Action or form PTO	-152.
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority document copies of the priority do	nts have been received. nts have been received in Applica onty documents have been received au (PCT Rule 17.2(a)).	ition No ved in this National St	age
* See the attached detailed Office action for a lis	st of the certified copies not receiv	ved.	
Attachment(s)			
Notice of References Cited (PTO-892)	4) 🔲 Interview Summar	y (PTO-413)	
2)	Paper No(s)/Mail [Date Patent Application (PTO-1	52)
D. L. L. J. C. C.	· · · · · · · · · · · · · · · · · · ·		

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Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which the subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-4, 10-11, 14-18, 33, 34 and 41 are rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal et al. (US 6,365,486 B1) in view of Huang et al. (US 6,146,941).

Agarwal teaches a method wherein:

providing a substrate 10 having an untreated dielectric layer 16:

the untreated dielectric layer does not comprise metal atoms;

the untreated dielectric layer comprises a silicon containing dielectric compounds;

the untreated dielectric layer comprises a material selected from the group consisting of SiO₂, SiN and other;

the exposing the dielectric layer to the excited iodine species is conducted at low pressure;

providing an iodine-containing precursor gas or surfactant species (col.5, lines 1-23);

generating a plasma discharge to create excited iodine species from the iodinecontaining precursor gas;

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exposing the dielectric layer to the excited iodine species to form a plasmatreated dielectric layer.

Reference: figs 1A-1C; cols 4-5, lines 33-23.

Agarwal teaches the features out lined above, but does not show exactly a method wherein the depositing a ruthenium thin film on the plasma-treated dielectric layer using a CVD and technique.

However, Huang teaches a method the depositing a ruthenium thin film 218 or 220 on the plasma-treated dielectric layer 216 or 220 (which making by APCVD or sputtering under the influence of plasma) using a CVD technique (figs. 1E-1H and 2A-2F with corresponding text).

Also, with respect to claims 10 and 11 Huang teaches a method for Ru thin film deposition wherein thin film containing ruthenium atoms or ruthenium oxide (col. 6, lines 16-22 and claims 14,23).

Consequently, it would have been obvious to one of ordinary skill in the art to apply method of Agarwal to obtain dielectric substrate treatment and ruthenium layer as taught by Agarwal/Huang.

Claims 6,7,12, 20-22 and 35 rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal et al. (US 6,365,486 B1) and in view of Pyo (US 6,593,236 B2) cited by applicant.

Agarwal teaches the features out lined above, but does not show exactly a method wherein the iodine-containing precursor gas comprises molecules selected from the group consisting of C_2H_5I , and other organic iodines, including I_2 .

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However, Pyo teaches a method wherein the iodine-containing precursor gas comprises molecules selected from the group consisting of C_2H_5I , and other organic iodines, including I_2 (col. 2, lines 40-55; claims 7-10).

Therefore, it would have been obvious to one of ordinary skill in the art to use C_2H_5I , and other organic iodines, including I_2 as iodine-containing precursor gas as taught by Agarwal/Poy.

Claims 8-9,31,32 rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal /Huang and in view of Vaartstra et al. (US 6,074,945).

Agarwal/ Huang teaches the features out lined above, but does not show exactly a method wherein the depositing a ruthenium thin film comprises using a MOCVD or an ALD technique.

However, Vaartstra et al. (US 6,074,945) teaches a method wherein the depositing a ruthenium thin film comprises using a MOCVD or an ALD technique (col.5, lines 54-62; col.6, lines 27-51).

Therefore, it would have been obvious to one of ordinary skill in the art to use the MOCVD or the ALD technique as taught by Agarwal/ Huang/ Vaartstra.

Claims 13, 36, 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal /Huang and in view of Lane et al. (US 6,812,143 B2)

Agarwal/ Huang teaches the features out lined above, but does not show exactly a method wherein the depositing the ultra-thin ruthenium film having a thickness in a range of about from 1 nm to 20 nm.

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However, Lane teaches a method wherein the depositing the ultra-thin ruthenium film having a thickness in a range of about from 1 nm to 40 nm (col. 9, lines 63-64).

Therefore, it would have been obvious to one of ordinary skill in the art to deposit Ru film with thickness as taught by Agarwal/ Huang/ Lane.

Claims 37-39 rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal /Huang and in view of Vaartstra et al. (US 6,074,945).

Agarwal/ Huang teaches the features out lined above, but does not show exactly a method wherein the depositing a second metal layer on ruthenium thin film.

However, Vaartstra et al. (US 6,074,945) teaches a method wherein the depositing a second metal layer (copper) on the ruthenium thin film (col.6, lines 6-18).

Therefore, it would have been obvious to one of ordinary skill in the art to use the second metal layer as taught by Agarwal/ Huang/ Vaartstra.

Claims objected

Claims 5, 19 and 23-30 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Victor Yevsikov whose telephone number is (571) 272-1910. The examiner can normally be reached on Monday –Thursdays 8:00-5:30.

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If attempts to reach the examiner by telephone are unsuccessful, examiner's supervisor, William B. Baumeister, can be reached on (571) 272-1722. The fax phone numbers for the organization where this application or processing is assigned is (703) 873-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published application may be obtained from either Private PAIR or Public PAIR. Status information for unpublished application is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

V. Juston

Victor Yevsikov Examiner Art Unit 2891

June 3, 2005

B. WILLIAM BAUMEISTER
SUPERVISORY PATENT EXAMINER